

UNITED STATES PATENT AND TRADEMARK OFFICE  
**CERTIFICATE OF CORRECTION**

PATENT NO. : 7,196,417 B2  
APPLICATION NO. : 10/626418  
DATED : March 27, 2007  
INVENTOR(S) : Tomohei Sugiyama et al.

Page 1 of 1

It is certified that error appears in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

Column 1, line 28, please delete "in thermal" and insert therefore -- in the thermal --;

Column 1, line 29, please delete "Si or other" and insert therefore -- Si or any other --;

Column 1, line 30, please delete "5 and Al" and insert therefore -- 5, and Al --;

Column 2, line 60, please delete "unsintered Sic particles" and insert therefore -- unsintered SiC particles --;

Column 2, line 67, please delete "expan" and insert therefore -- expan- --;

Column 4, line 5, please delete "as low thermal" and insert therefore -- as low a thermal --;

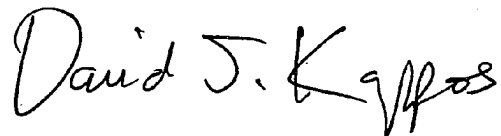
Column 4, line 55, please delete "The mold/melt temperature is set to" and insert therefore -- The mold/melt temperature is set to 700/800°C for each of Samples S5 to S8. --;

Column 5, line 61, please delete "as heat spreader" and insert therefore -- as a heat spreader --; and

Column 6, line 7, please delete "as heat spreader" and insert therefore -- as a heat spreader --.

Signed and Sealed this

Thirteenth Day of October, 2009

A handwritten signature in black ink, reading "David J. Kappos". The signature is written in a cursive, flowing style with a large initial 'D' and a stylized 'K'.

David J. Kappos  
*Director of the United States Patent and Trademark Office*